

LISTING OF THE CLAIMS:

28. (currently amended) A method of constructing a multi-chip package, comprising:  
attaching a semiconductor die to a slug;  
attaching the slug to a base of a package;  
electrically connecting a said semiconductor die to at least one of a plurality of shelves of the package;  
electrically connecting a flip-chip to a substrate; and  
attaching ~~the side of said substrate that does not have the flip-chip mounted to it~~ to one of said plurality of shelves; and  
disposing a seal between a base of said substrate and the one of said plurality of shelves to which said substrate is attached, wherein a cavity is formed between said substrate and said base of said package, the cavity comprising only said semiconductor die.
29. (previously presented) The method of claim 28, further comprising electrically connecting said substrate to at least one of said plurality of shelves.
30. (previously presented) The method of claim 29, wherein electrically connecting said substrate to at least one of said plurality of shelves comprises electrically connecting said substrate to at least one of said plurality of shelves with at least one bond wire.

31. (currently amended) The method of claim 28, wherein attaching ~~the side of~~ said substrate ~~that does not have the flip chip mounted to it~~ to one of said plurality of shelves provides a lid above said semiconductor die.

32. (previously presented) The method of claim 28, further comprising electrically testing said electrically connected flip-chip before attaching of said substrate to said one of said plurality of shelves.

33. (previously presented) The method of claim 28, wherein electrically connecting said flip-chip to said substrate comprises electrically connecting said flip-chip to said substrate with solder balls.

34. (previously presented) The method of claim 28, further comprising covering said flip-chip with an encapsulant.

35. (Canceled))

36. (previously presented) The method of claim 28, wherein electrically connecting said semiconductor die to said at least one of a plurality of shelves comprises electrically connecting a CPU chip to said at least one of said plurality of shelves.

37. (previously presented) The method of claim 28, wherein electrically connecting said flip-chip to said substrate comprises electrically connecting a memory cache flip-chip to said substrate.

38. (previously presented) The method of claim 28, wherein electrically connecting said semiconductor die to at least one of said plurality of shelves comprises electrically connecting said semiconductor die to said at least one of a plurality of shelves with at least one bond wire.

39. (Currently amended) ~~The method of claim 28, further including attaching said semiconductor die to a slug. The method of claim 28 wherein attaching said semiconductor die to a slug comprises attaching said semiconductor die to a slug comprising copper.~~

40. (Canceled)